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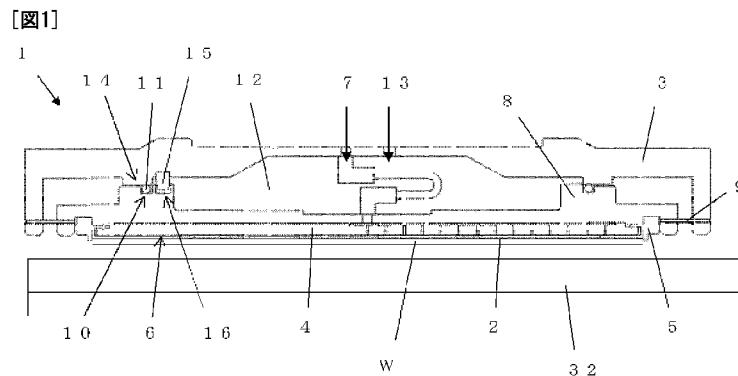
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(54) Title: ABRASIVE HEAD AND ABRADING DEVICE

(54) 発明の名称: 研磨ヘッド及び研磨装置



(57) Abstract: Disclosed is an abrasive head wherein in the lower portion of the abrasive head body, there are provided a rubber film held by a disk-shaped intermediate plate, and an annular guide ring disposed around the rubber film; and wherein the back surface of a workpiece is held on the lower surface of the rubber film, and the front surface of the workpiece is brought into sliding contact with an abrasive cloth bonded to a surface plate, resulting in the workpiece being abraded. This abrasive head has a base member which holds the guide ring and the intermediate plate in such a way that the lower surface of the guide ring does not come into contact with the abrasive cloth during abrasion and which is connected to the abrasive head body via an elastic film. A portion of the upper surface of the base member comes into contact with the abrasive head body, resulting in the axial displacement of the base member being restricted. Furthermore, due to the elastic film, the base member is capable of undergoing radial displacement during abrasion. Thus provided are an abrasive head and an abrading device whereby a certain degree of high flatness and high uniformity of abrasion margin can be obtained in a stable manner during abrasion of a workpiece, whereby furthermore, it is possible to obtain a workpiece having only a small number of minute particles 45 nm or more in size, and which can be used in both a rough abrasion process and a finish abrasion process.

(57) 要約:

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